

ABSTRACT

According to the present invention, it is possible to provide a pressure-sensitive adhesive tape for semiconductor substrate fabrication, including a base material, and a pressure-sensitive adhesive layer laminated on one surface of the base material, in which the pressure-sensitive adhesive tape is used for a process of performing fabrication in which when a sealed semiconductor connection including a substrate, a plurality of semiconductor elements disposed on the substrate, and a sealing portion sealing the plurality of semiconductor elements is cut in a thickness direction thereof to obtain a plurality of semiconductor sealing bodies, the sealed semiconductor connection is temporarily fixed to the base material through the pressure-sensitive adhesive layer, the pressure-sensitive adhesive layer contains a peeling agent for reducing adhesiveness to the sealing portion when the semiconductor sealing bodies are peeled from the pressure-sensitive adhesive tape for semiconductor substrate fabrication, the sealing portion is formed of a sealing material containing an epoxy group-containing compound, the epoxy group-containing compound has a double bond in a molecular structure thereof, and the peeling agent is a silicone-based oil or a fluorine-based surfactant.